

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of : **Confirmation No. 8728**
Norio KIMURA et al. : **Docket No. 2000-1761A**
Serial No. 09/742,386 : **Group Art Unit 1763**
Filed December 22, 2000 :

APPARATUS AND METHOD FOR
PROCESSING SEMICONDUCTOR
SUBSTRATE

PRELIMINARY AMENDMENT

Assistant Commissioner for Patents,
Washington, D.C.

Sir:

Prior to examination of the above-referenced U.S. patent application, kindly amend the application as follows:

IN THE CLAIMS

Please add the following new claims:

63. A semiconductor substrate processing apparatus, comprising:
- a carry-in and carry-out section for carrying in and carrying out a semiconductor substrate having a surface on which a circuit is formed;
 - a plated metal film forming unit for forming a plated metal film on said semiconductor substrate which has been carried in;
 - an annealing unit for annealing said semiconductor substrate;
 - a film thickness measuring unit for measuring and/or detecting a film thickness of said film and/or a surface state of said film formed on said semiconductor substrate; and
 - a transport mechanism for transporting said semiconductor substrate between said units.